

# TLIN1029A-Q1 Functional Safety FIT Rate, FMD and Pin FMA



## Table of Contents

1 Overview.....	2
2 Functional Safety Failure In Time (FIT) Rates.....	3
3 Failure Mode Distribution (FMD).....	4
4 Pin Failure Mode Analysis (Pin FMA).....	5

### Trademarks

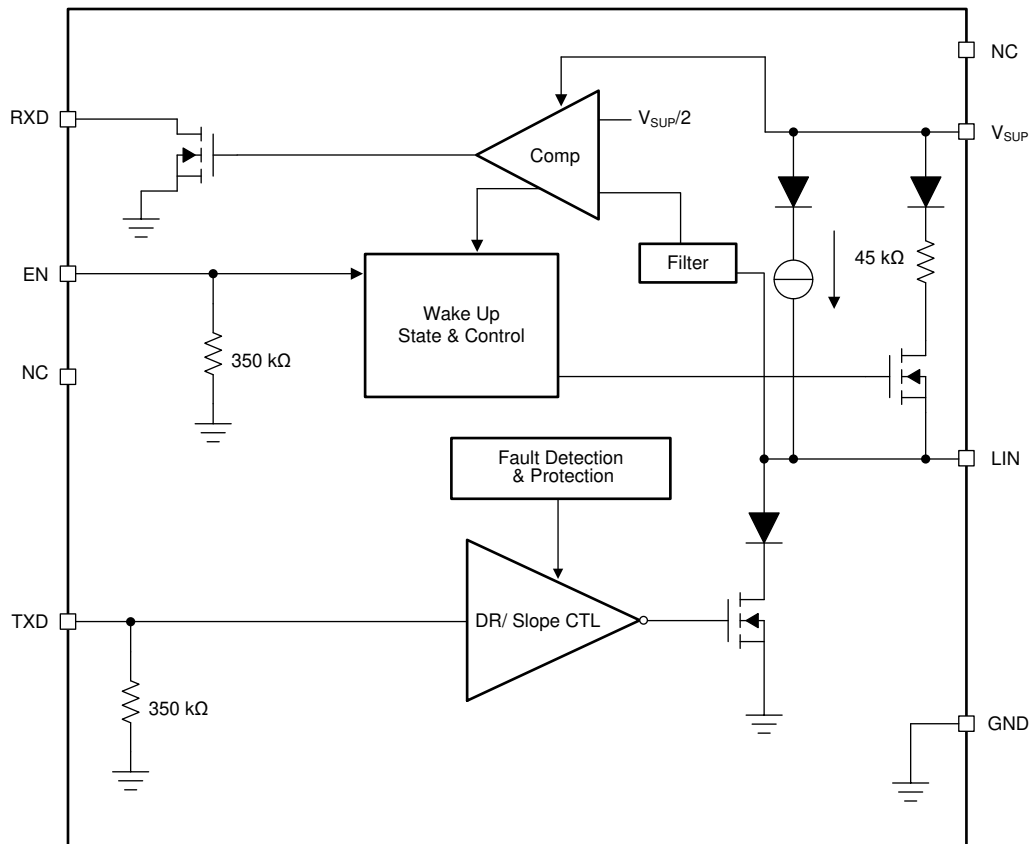
All trademarks are the property of their respective owners.

## 1 Overview

This document contains information for the TLIN1029A-Q1 which is a local interconnect network (LIN) transceiver in 8-pin SOIC (D) and 8-pin VSON (DRB) packages to aid in a functional safety system design. Information provided are:

- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device
- Pin failure mode analysis (Pin FMA)

Figure 1-1 shows the device functional block diagram for reference.



**Figure 1-1. Functional Block Diagram**

TLIN1029A-Q1 was developed using a quality-managed development process, but was not developed in accordance with the IEC 61508 or ISO 26262 standards.

## 2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for the TLIN1029A-Q1 based on two different industry-wide used reliability standards:

- [Table 2-1](#) provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- [Table 2-2](#) provides FIT rates based on the Siemens Norm SN 29500-2

**Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11**

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10 <sup>9</sup> Hours) (DRB)	FIT (Failures Per 10 <sup>9</sup> Hours) (D)
Total Component FIT Rate	7	11
Die FIT Rate	3	4
Package FIT Rate	4	7

The failure rate and mission profile information in [Table 2-1](#) comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 100 mW
- Climate type: World-wide Table 8
- Package factor ( $\lambda_3$ ): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

**Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2**

Table	Category	Reference FIT Rate	Reference Virtual T <sub>J</sub>
5	CMOS, BICMOS	25 FIT	55°C

The Reference FIT Rate and Reference Virtual T<sub>J</sub> (junction temperature) in [Table 2-2](#) come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

### 3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for the TLIN1029A-Q1 in [Table 3-1](#) comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

**Table 3-1. Die Failure Modes and Distribution**

Die Failure Modes	Failure Mode Distribution (%)
Transmitter fail	56%
Receiver fail	3%
Logic I/O fail or state control fail	11%
Global power management fail	30%

## 4 Pin Failure Mode Analysis (Pin FMA)

This section provides a Failure Mode Analysis (FMA) for the pins of the TLIN1029A-Q1. The failure modes covered in this document include the typical pin-by-pin failure scenarios:

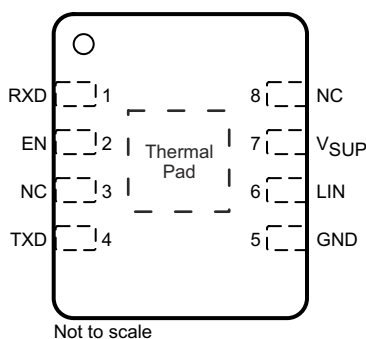
- Pin short-circuited to Ground (see [Table 4-2](#))
- Pin open-circuited (see [Table 4-3](#))
- Pin short-circuited to an adjacent pin (see [Table 4-4](#))
- Pin short-circuited to supply (see [Table 4-5](#))

[Table 4-2](#) through [Table 4-5](#) also indicate how these pin conditions can affect the device as per the failure effects classification in [Table 4-1](#).

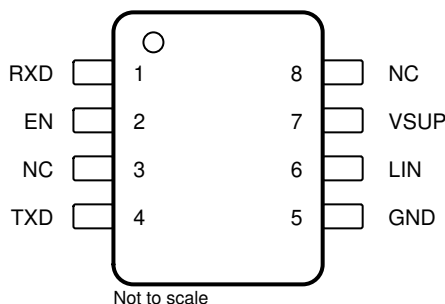
**Table 4-1. TI Classification of Failure Effects**

Class	Failure Effects
A	Potential device damage that affects functionality
B	No device damage, but loss of functionality
C	No device damage, but performance degradation
D	No device damage, no impact to functionality or performance

[Figure 4-1](#) shows the device pin diagram. For a detailed description of the device pins, please refer to the *Pin Configuration and Functions* section in the TLIN1029A-Q1 data sheet.



**Figure 4-1. DRB Pin Diagram**



**Figure 4-2. D Pin Diagram**

Following are the assumptions of use and the device configuration assumed for the pin FMA in this section:

- All conditions within the recommended operating conditions

**Table 4-2. Pin FMA for Device Pins Short-Circuited to Ground**

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
RXD	1	RXD biased dominant, no communication from LIN bus to MCU possible	B
EN	2	Device may only operate in Standby Mode after power-on. If short occurs in Normal mode, the part would be forced to enter sleep mode and could disable LIN communication	B
NC	3	No impact to performance	D
TXD	4	TXD biased dominant, no communication from MCU to LIN bus possible	B
GND	5	None	D
LIN	6	LIN biased dominant, no LIN communication possible	B
V <sub>SUP</sub>	7	Device is unpowered and will not function	B
NC	8	No impact to performance	D

**Note**

DRB package includes a thermal pad

**Table 4-3. Pin FMA for Device Pins Open-Circuited**

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
RXD	1	No communication from LIN bus to MCU possible	B
EN	2	Biased low due to internal pull-down so device in standby mode	B
NC	3	No impact to performance	D
TXD	4	No communication from MCU to LIN bus possible	B
GND	5	Device is unpowered and will not function	B
LIN	6	No LIN communication possible	B
V <sub>SUP</sub>	7	Device is unpowered and will not function	B
NC	8	No impact to performance	D

**Note**

DRB package includes a thermal pad

**Table 4-4. Pin FMA for Device Pins Short-Circuited to Adjacent Pin**

Pin Name	Pin No.	Shorted to	Description of Potential Failure Effect(s)	Failure Effect Class
RXD	1	EN	Device will go into sleep mode when a dominant bit is received on the LIN bus, disabling communication	B
EN	2	NC	No impact to performance	D
NC	3	TXD	No impact to performance	D
GND	5	LIN	LIN biased dominant, no LIN communication possible	B
LIN	6	V <sub>SUP</sub>	LIN biased recessive, no LIN communication possible	B
V <sub>SUP</sub>	7	NC	No impact to performance	D

**Note**

The DRB package includes a thermal pad. There is a chance the thermal pad is soldered down and could short to any pin on device. What the thermal pad is soldered to determines the behavior. Example: if soldered to a ground plane then the adjacent pins would behave as if shorted to ground.

**Table 4-5. Pin FMA for Device Pins Short-Circuited to  $V_{SUP}$  supply**

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
RXD	1	Absolute maximum voltage violation, transceiver may be damaged	A
EN	2	Absolute maximum voltage violation, transceiver may be damaged	A
NC	3	No impact to performance	D
TXD	4	Absolute maximum voltage violation, transceiver may be damaged	A
GND	5	Device is unpowered and will not function	B
LIN	6	LIN biased recessive, no LIN communication possible	B
VSUP	7	None	D
NC	8	No impact to performance	D

---

**Note**

DRB package includes a thermal pad

---

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](http://ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2022, Texas Instruments Incorporated